

# Pico-Second Laser and Broad Argon Beam Tools For Characterization Of Advanced Packages And Devices

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# Where Did this Product Come From?

Joint effort between Gatan-3D-Micromac and Fraunhofer-Halle

3D-Micromac AG

Technologie-Campus 8

09126 Chemnitz, Germany

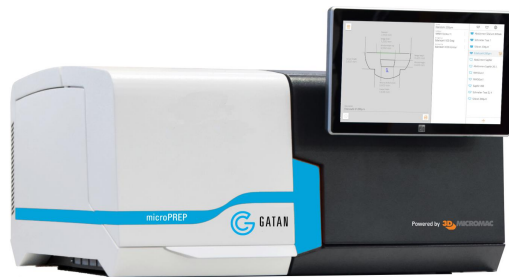
<http://3d-micromac.com>



# Overview

**Picosecond laser ablation sample preparation tool to rapidly remove material for electron and x-ray microscopy. Complements or replaces mechanical, focused and broad ion beam (FIB and BIB) tools.**

- Table top system that operates with compressed air
- Cross section packages as large as 110 x 110 x 4 mm
- Simple interface to adjust laser power level
- Diode pumped solid state laser (Wave length: 532 nm)



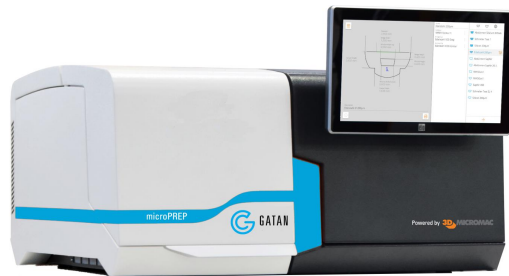
# Large Area and Volume Capabilities

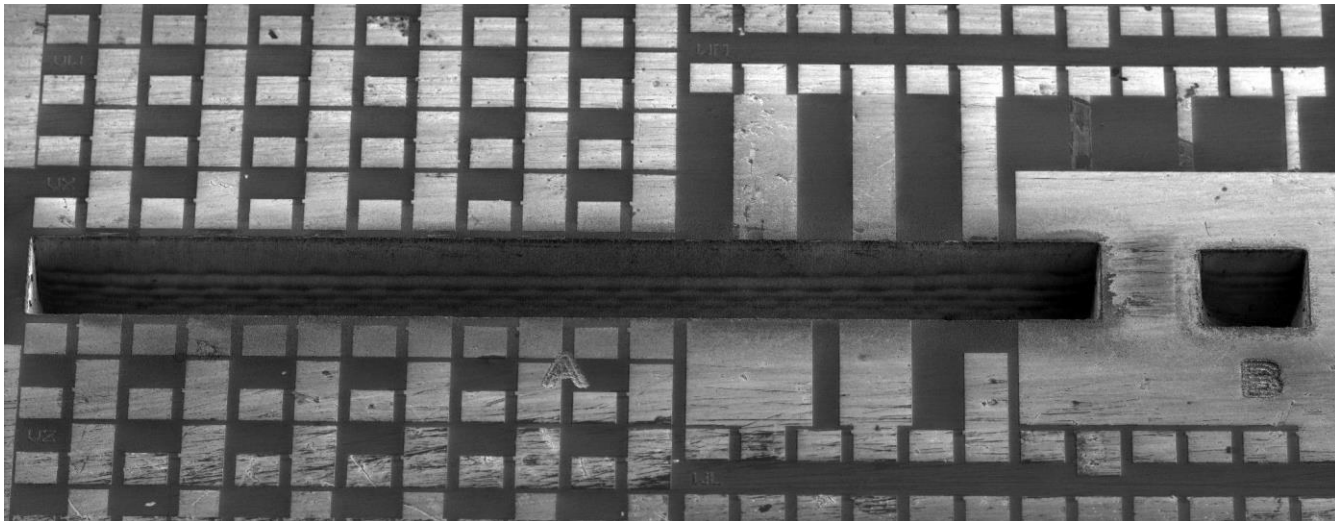
## Box cuts

- Excavate large volumes  
3.0 x 0.3 x 0.3 mm (L x W x D) in <25 min

## Line cuts

- Cross-section large samples  
25 x 1.5 mm (L x D) in 15 – 25 min



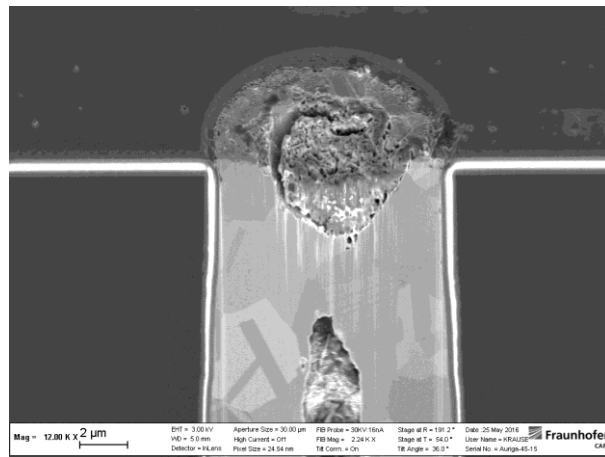
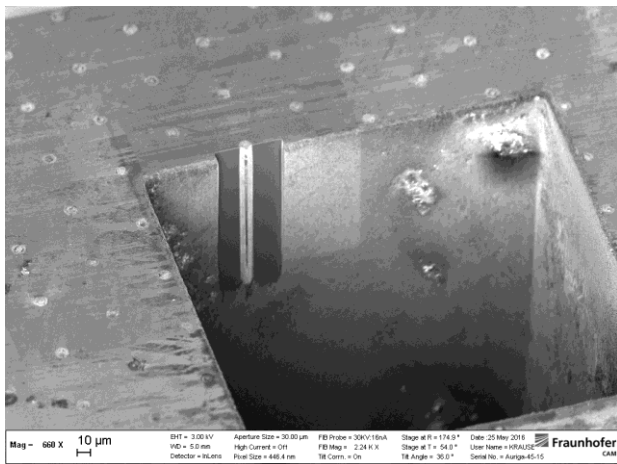


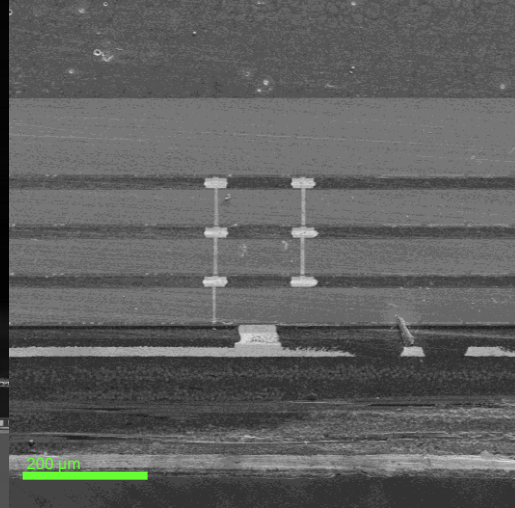
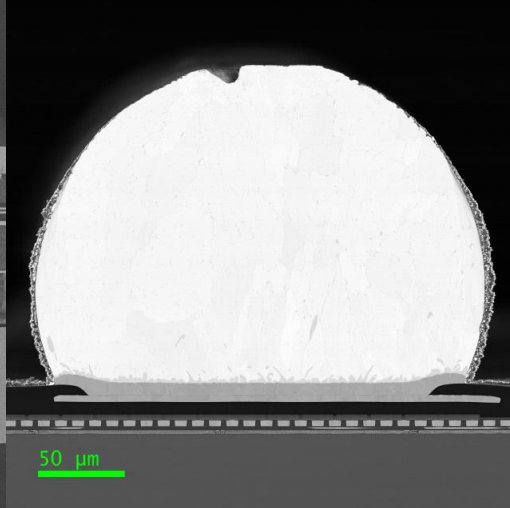
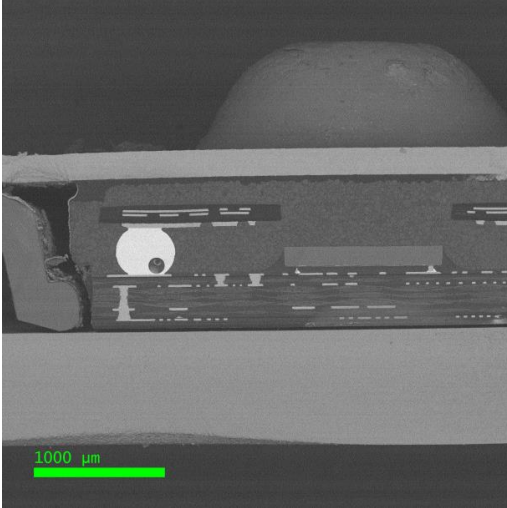
## Quickly Trench Large Areas – Silicon with TSV's



Sample	Size (mm)	microPREP (actual)	Ga FIB (calc.)
#70	0.3 x 0.3 x 0.3	3 min, 40 s	17.5 days
#69	3.0 x 0.3 x 0.3	23 min, 40 s	0.5 years

# Post microPREP + Ga FIB





## Solutions for Dissecting Advanced Packages

- Deliver near perfect surface for high-resolution, analytical analysis for root cause determination
- Cross-section stacked devices and advanced packages
- Prepare large ROI within minutes



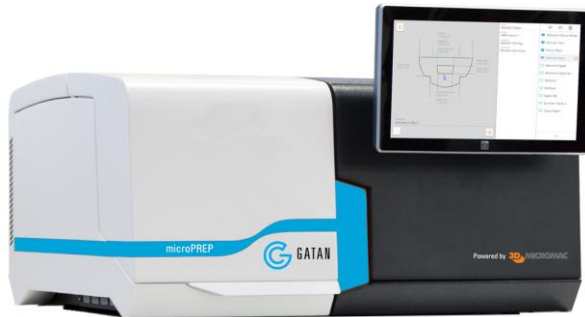
# Workflow for Sectioning Stacked Chips

microPREP

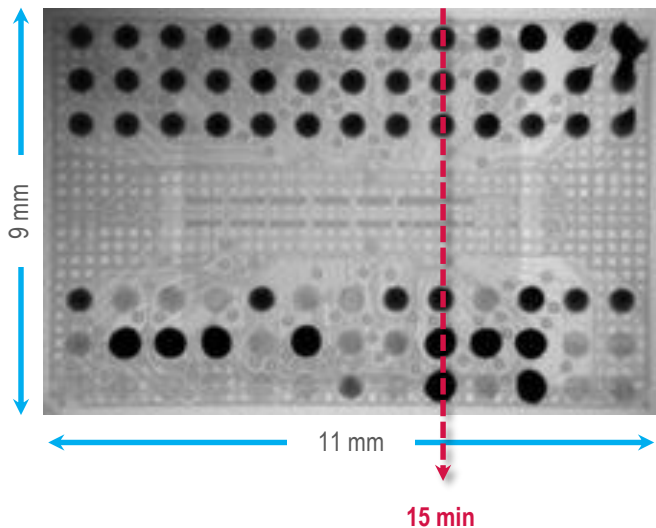
- Slice entirely through package
- Time = **15 min**

Ilion II

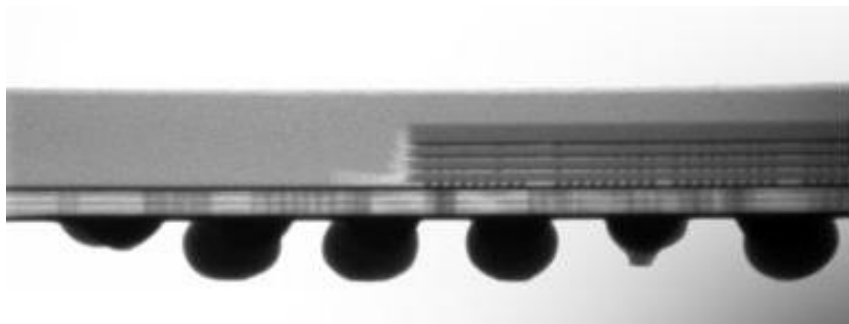
- Cross-section polish
- Time = **1 h**



Top view of multi-layer device



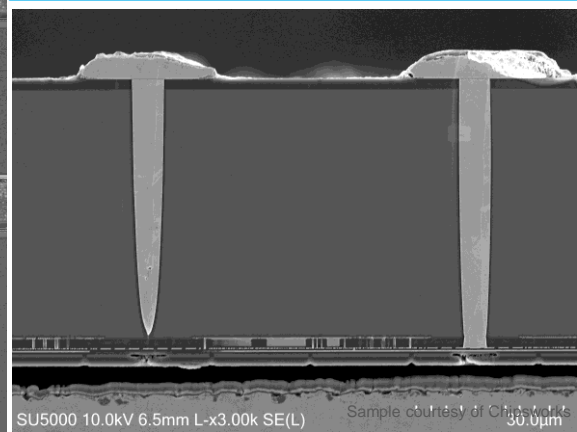
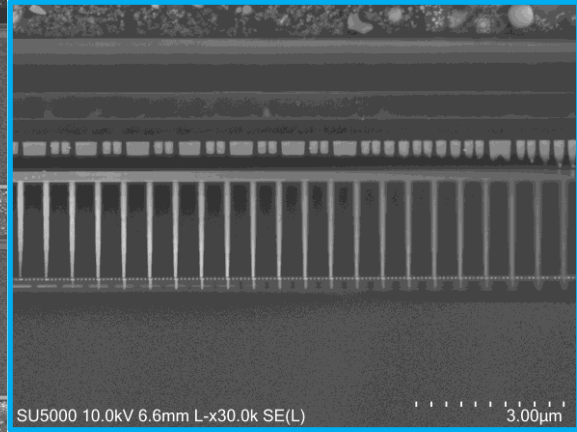
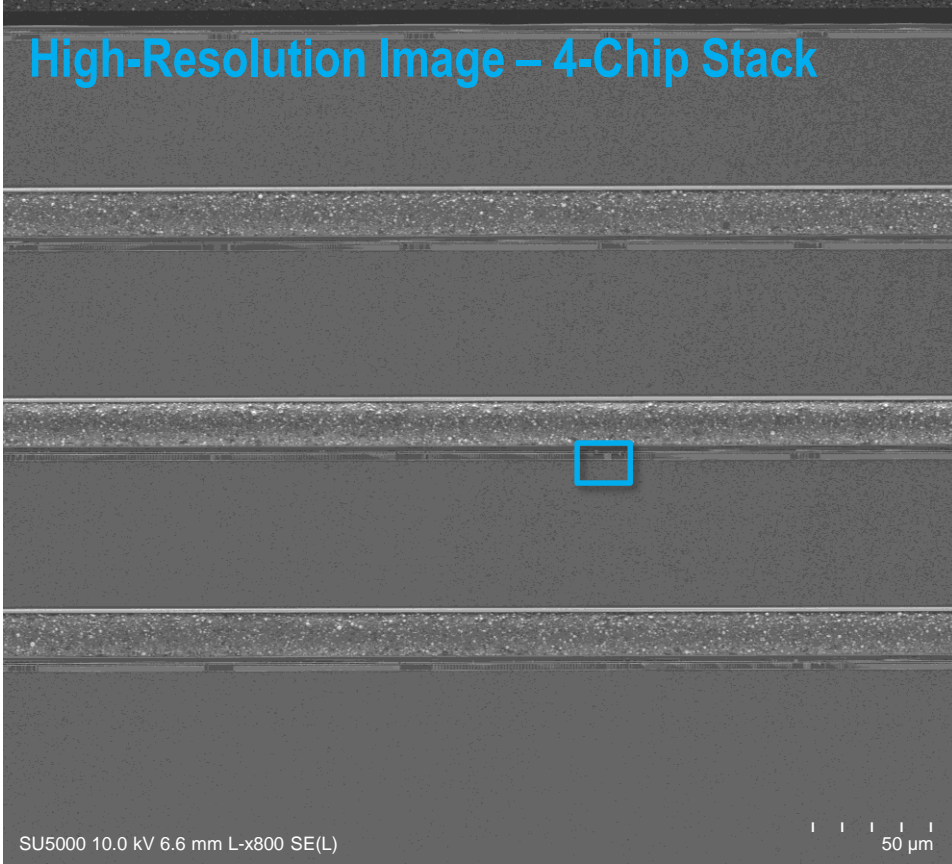
X-ray image of ROI



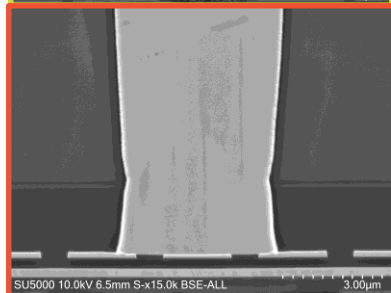
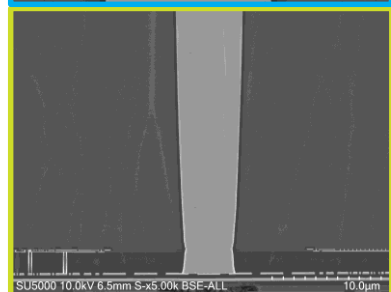
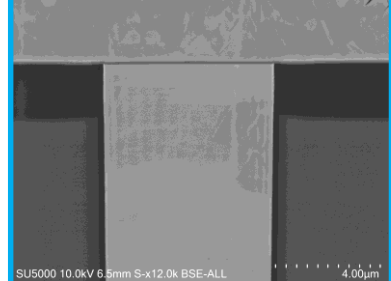
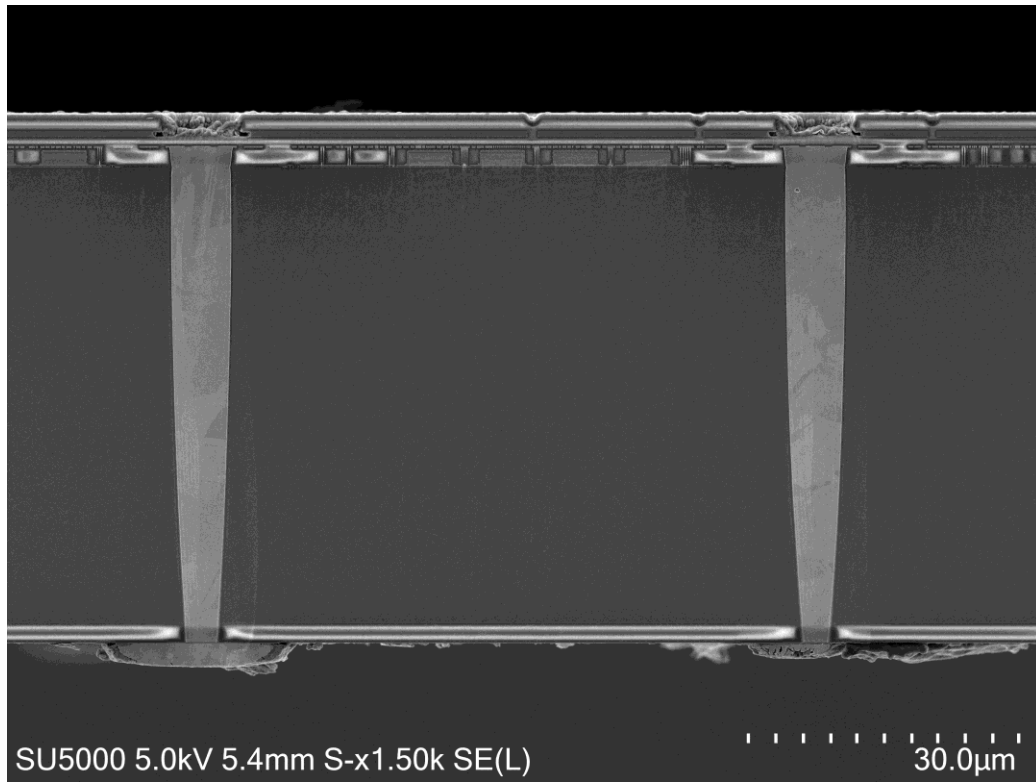
## Cross-Section Stacked Chip

- Cut through large, 4-layer stack (9 x 1.1 mm (L x D)) within 15 min

# High-Resolution Image – 4-Chip Stack



# Visualize Large Features – TSV



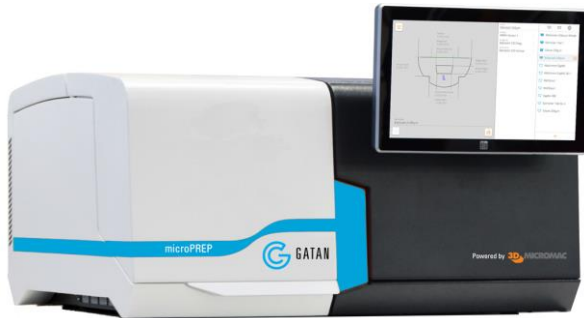
# Workflow for Sectioning Ball Bonds and Package

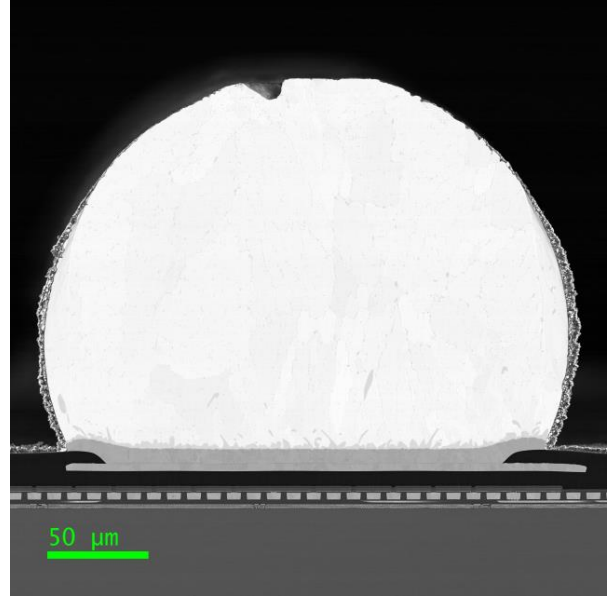
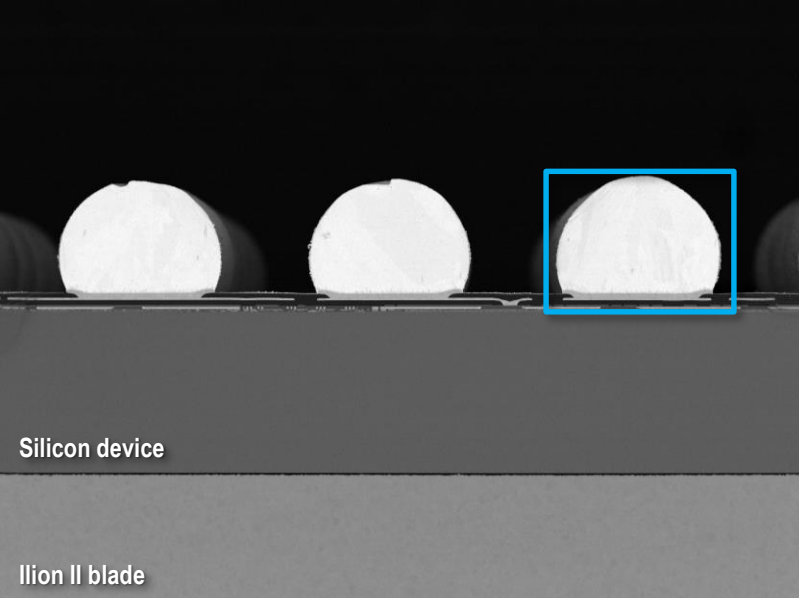
microPREP

- Slice entirely through package
- Time = 7 min

Ilion II

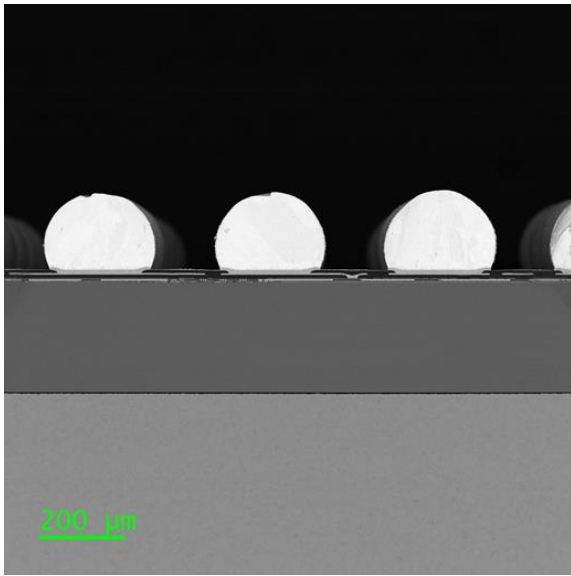
- Cross-section polish
- Time = 1 h



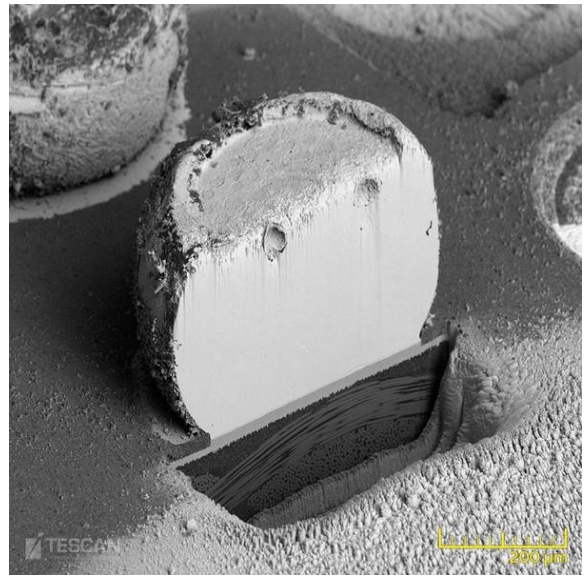


## Cross-Section Ball Bonds

- Cut through three ball bonds plus complete silicon device and package (11 x 0.5 mm (L x D)) within 7 min
- Post Ilion II polish within 1 h

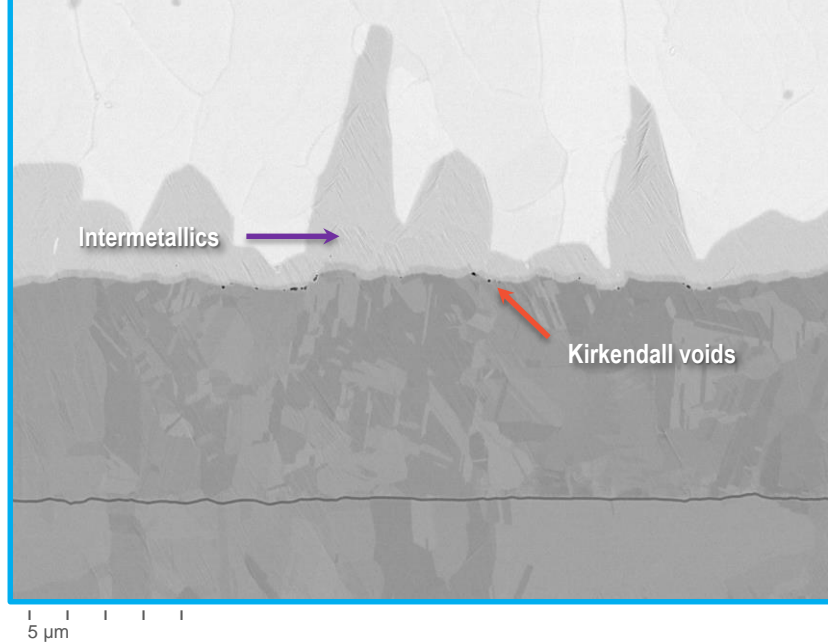
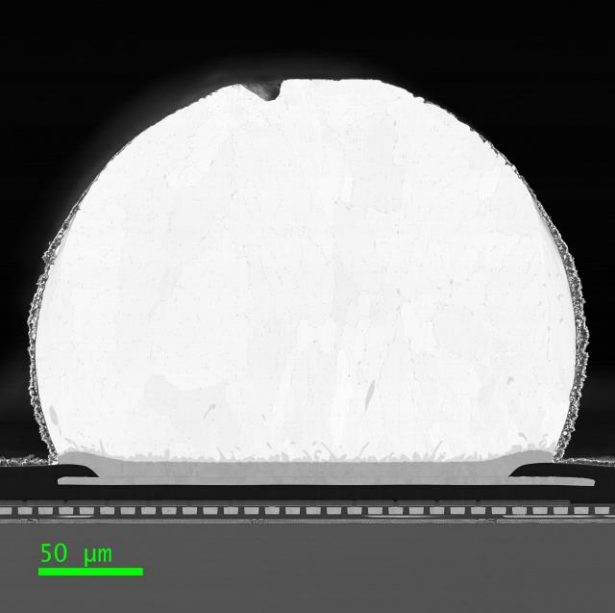


microPREP (7 min) + Ilion II (1 hr) result ROI 16 times larger than P-FIB



Cross-section of a solder ball with a diameter of 400 μm completed in **4 hr using Xe Plasma FIB** and Rocking Stage for a curtaining-free surface.

## Comparison microPREP + Ilion vs. Plasma FIB

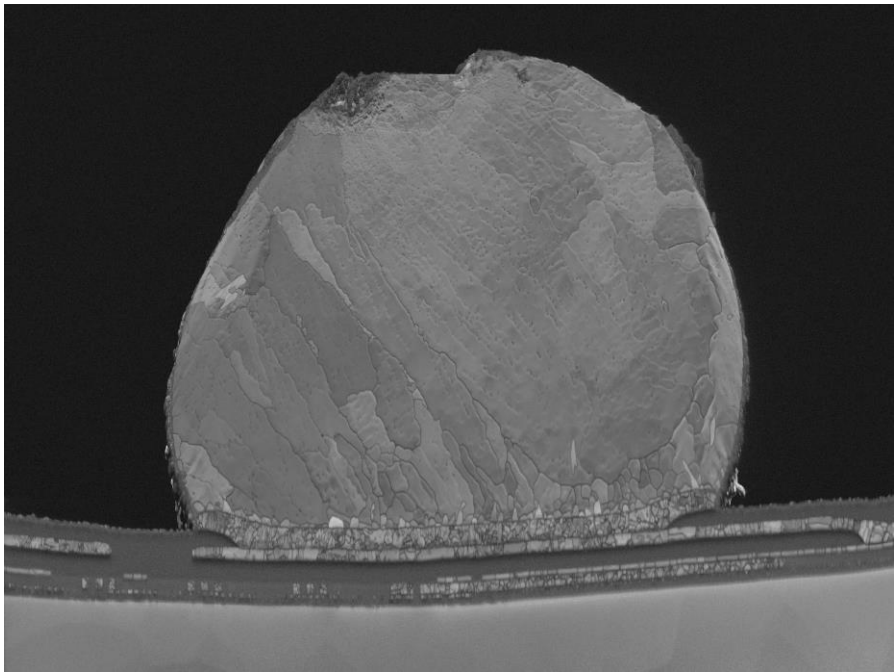


## High-Resolution Detail at the Interface

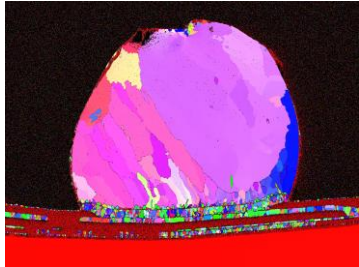
- Kirkendall voids indicate defect formation caused by different diffusion rates
- Presence of intermetallic compounds may point toward wire bond failures in device



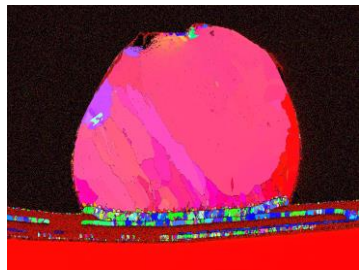
Band Contrast Image



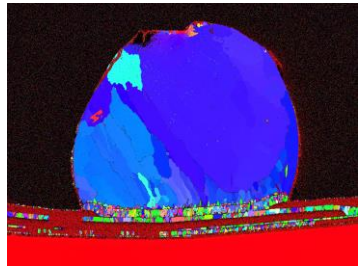
IPF X



IPF Y

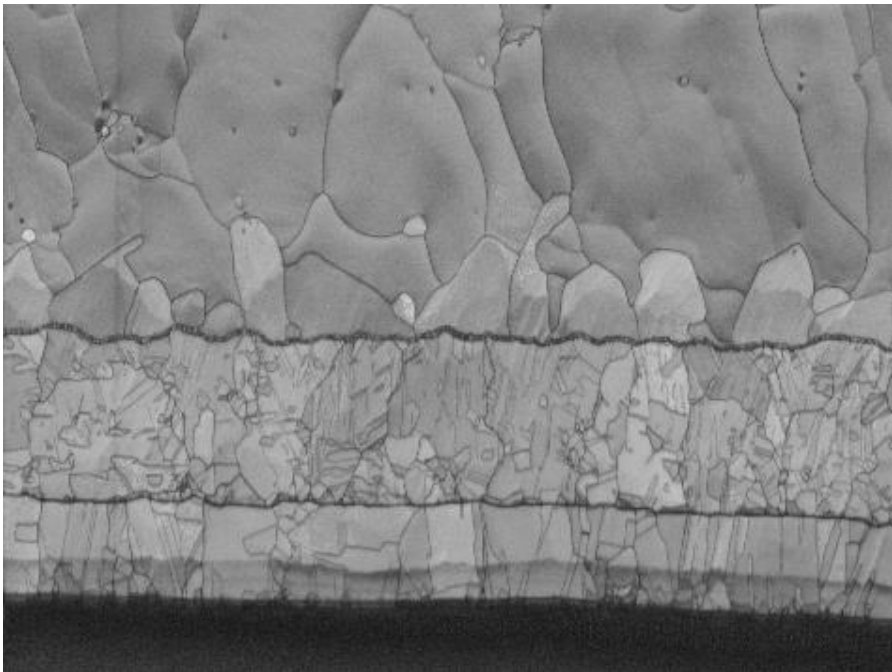


IPF Z

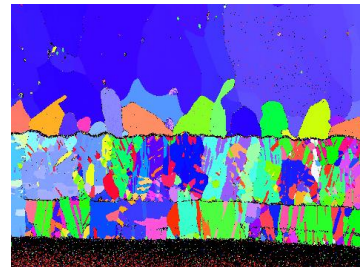


**EBSD MAPS of Ball Bond**

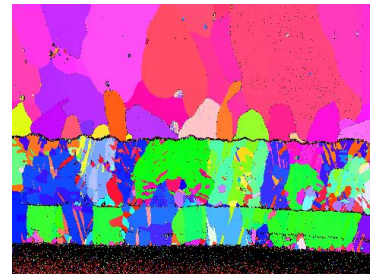
Band Contrast Image



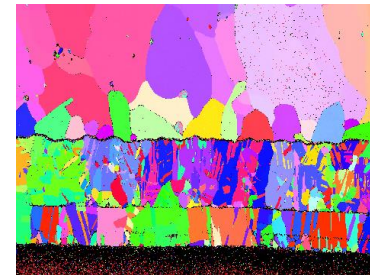
IPF X



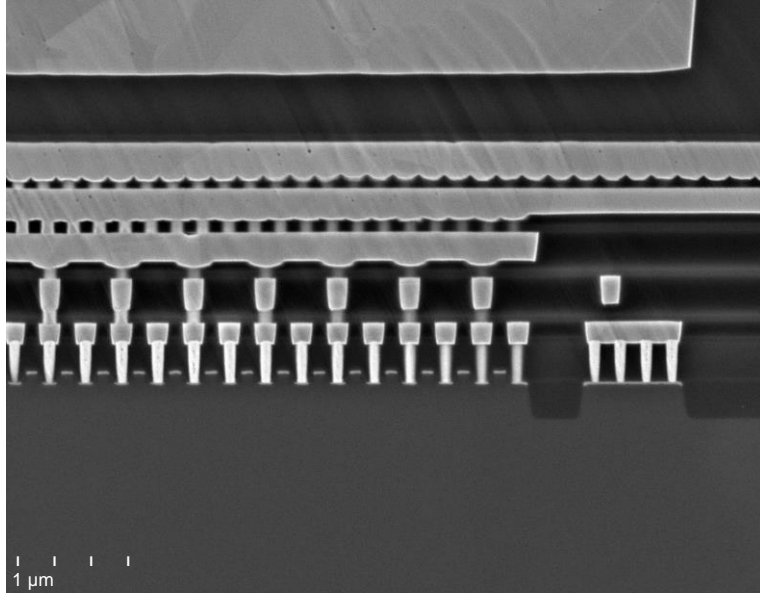
IPF Y



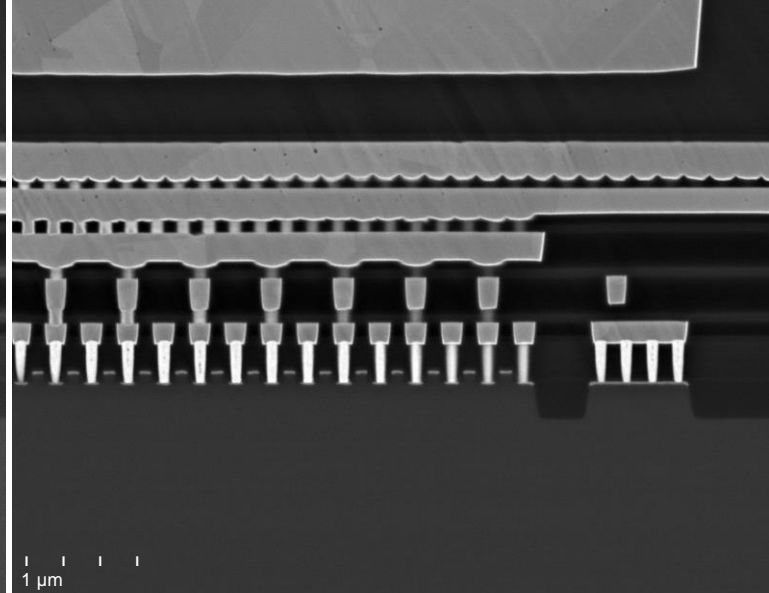
IPF Z



**EBSD of Ball Bond/UBM Interface**



Secondary Electron



Backscattered Electron



**Transistors Below the Ball Bond/UBM Layer**

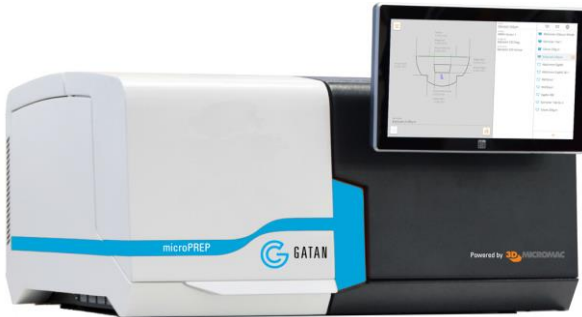
# Workflow for Sectioning Home Button

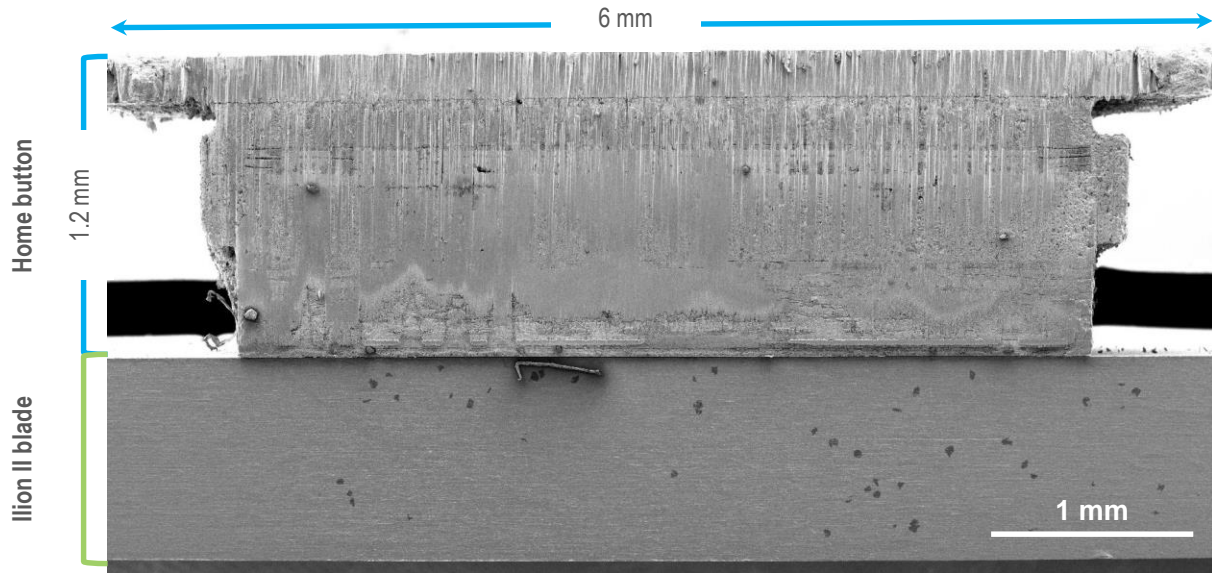
microPREP

- Slice entirely through package
- Time = **45 min**

Ilion II

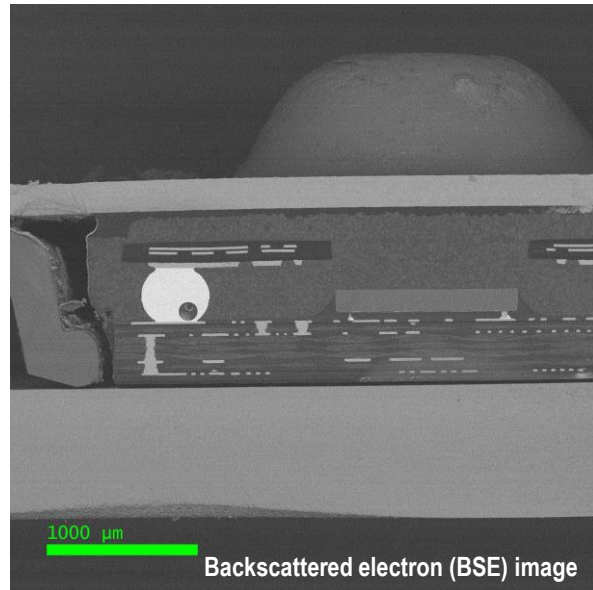
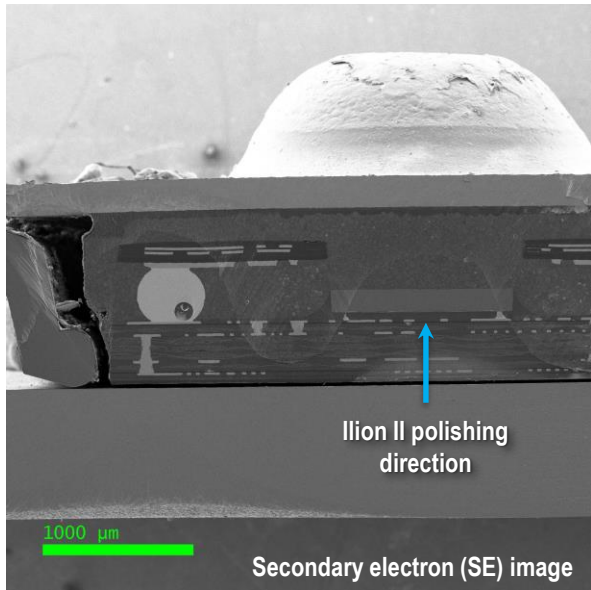
- Cross-section polish
- Time = **1 h**





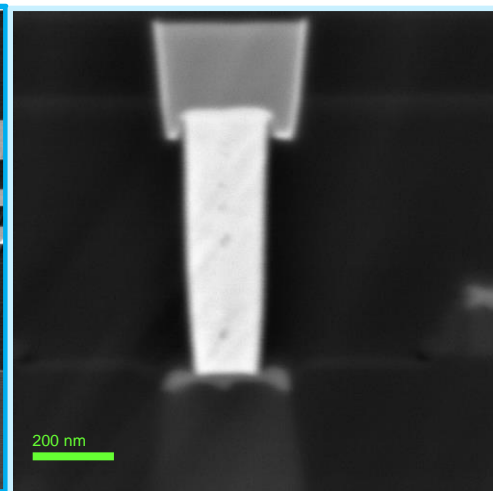
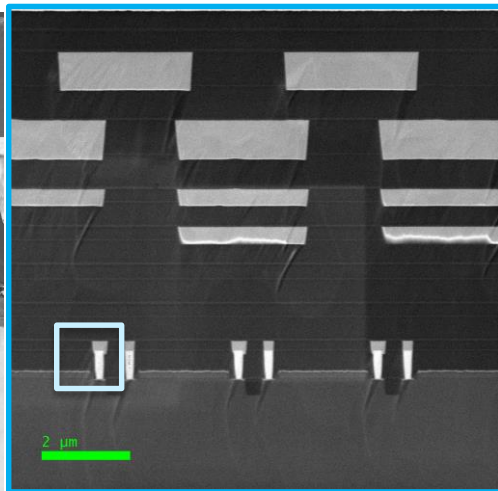
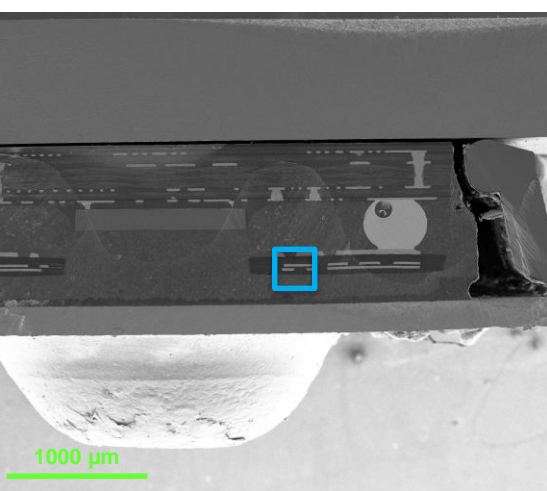
## Cross-Section Home Button in 45 min

- Shows initial cross-section made by the microPREP
- Follow-up with broad ion beam tool to polish



## Overview of Home Button





## Post Ilion Polish

# Summary

## Solutions for Dissecting Advanced Packages

- Deliver near perfect surface for high-resolution, analytical analysis for root cause determination
- Cross-section stacked devices and advanced packages
- Prepare large ROI within minutes

**microPREP opens opportunities to expand the size, volume and speed of preparing samples for**

- XRM samples
- Atom probe tips
- High volume TEM prep



# Thank You

